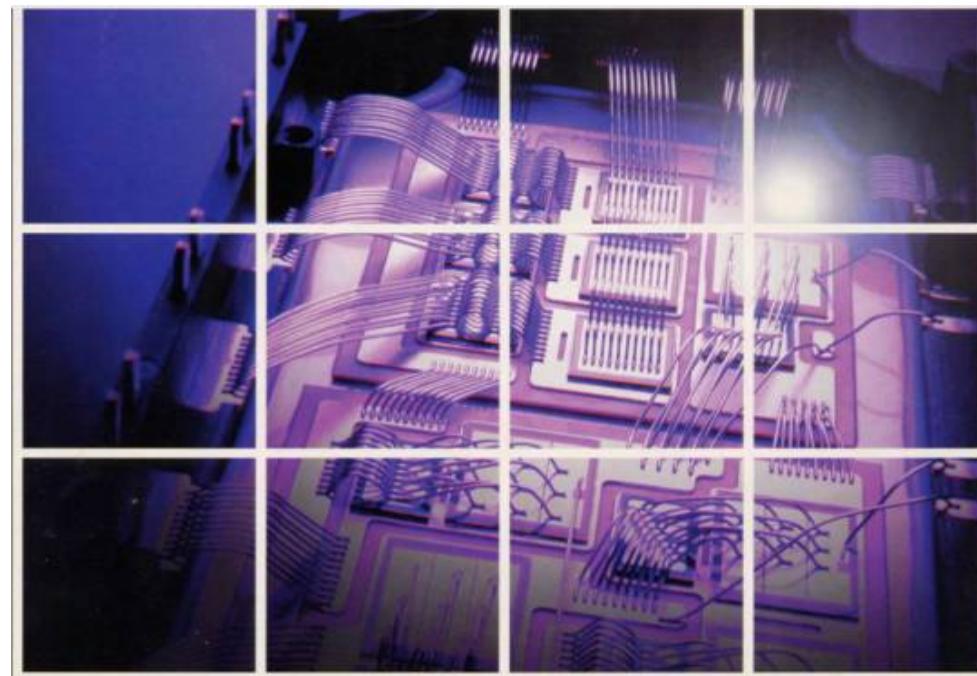


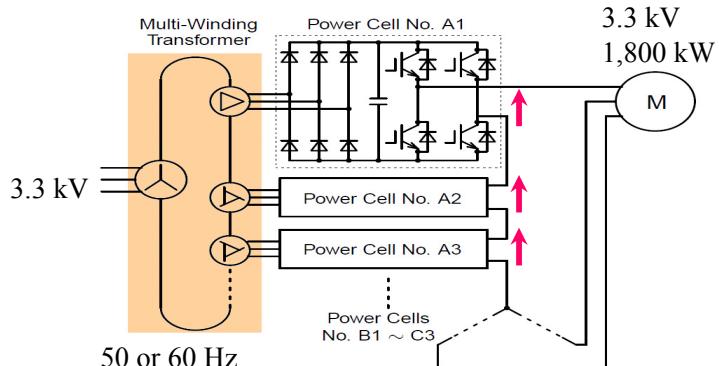
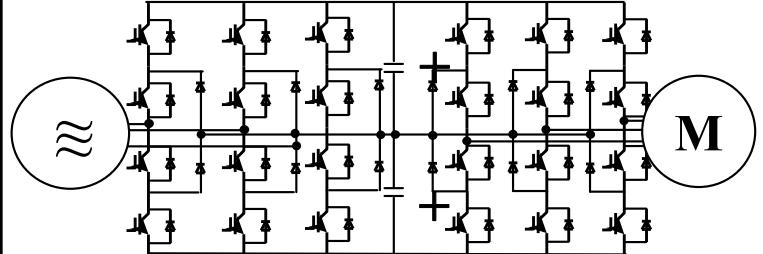
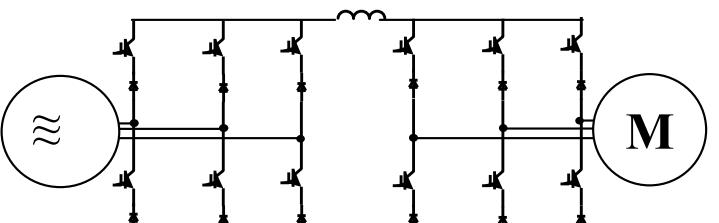
# **Fuji IGBT modules for MV , SVG inverter**



Device Application Technology Dept.  
Semiconductor Sales Div.  
Global Sales Group

- Topology in MV , SVG inverter
- Fuji IGBT modules for MV, SVG inverter
- Fuji solution in Gate Driver Unit (GDU) and Stack structure

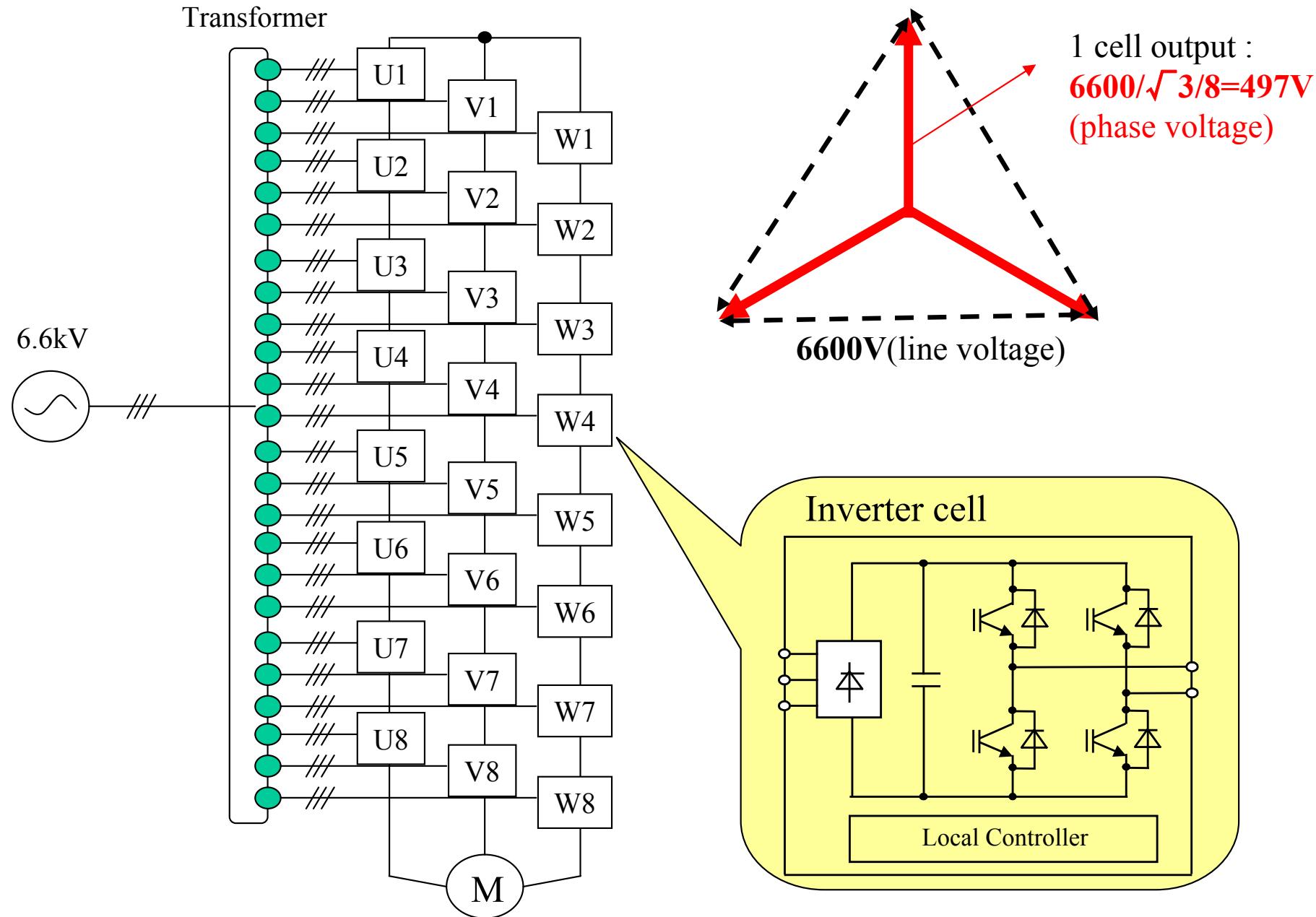
# Topology in MV , SVG inverter

	Topology (example)	Feature	Applicable device	Applicable rate
Unit serial multi-level (Robicon type)		<ul style="list-style-type: none"> <li>Topology is simple, easy maintenance, any output voltage can be obtained by unit cell serials</li> <li>Input-Transformer is necessary (high cost)</li> </ul>	1700V/100A~1200A Standard Module	60% Around the world (China etc.)
Direct 3 level Inverter		<ul style="list-style-type: none"> <li>Transformer less</li> <li>Topology is complicated</li> </ul>	3.3kV/800~1500A 4.5kV/400A~1500A HPM	30% Europe and America
Current type Inverter		<ul style="list-style-type: none"> <li>Reverse-blocking diode is necessary (Large loss)</li> </ul>	6.5kV/400A~1500A Press Pack(GCT)	10% Europe and America

# Topology in MV , SVG inverter

Field	Application	Topology			Function
		Unit serial multi-level	Direct 3 level	Current type	
Electric	Dust collecting fan	○	○	○	
	Boiler	○	○	○	
	Circulation pump	○	○	○	
Petroleum	Oil transfer pump	○	○	○	
	Ventilation fan	○	○	○	
	Compressor	-	○	○	Regeneration
Steel	Rolling	○	○	○	
	Ventilation fan	○	○	○	
	Pump	○	○	○	
Cement	Cooler dust collector	○	○	○	
	Material mill	○	○	○	
	Fan	○	○	○	
Paper	Pulp mill	-	○	○	Regeneration
Mining	Exhaust fan	○	○	○	
	Ventilation fan	○	○	○	
Transport	Conveyor	-	○	○	Regeneration
	Crane	-	○	○	Regeneration

# Topology - Unit serial multi-level circuit (6.6kV output)



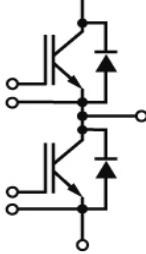
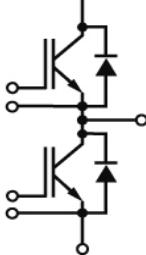
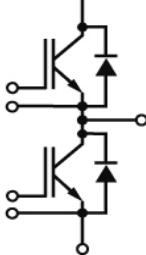
- Topology in MV , SVG inverter
- Fuji IGBT modules for MV, SVG inverter
- Fuji solution in Gate Driver Unit (GDU) and Stack structure

# Fuji IGBT module for MV , SVG inverter

AC output voltage	Inverter capacity (kVA)	Serial	VCES	Ic rating	IGBT P/N
3.3 kV	350	4	1700V	100A	2MBI100VA-170-50
	500	4	1700V	150A	2MBI150VH-170-50
	700	4	1700V	200A	2MBI200VH-170-50
	1050	4	1700V	300A	2MBI300VN-170-50
	1350	4	1700V	400A	2MBI450VN-170-50
	1600	4	1700V	300A x2	2MBI300VN-170-50
6.6 kV	720	8	1700V	100A	2MBI100VA-170-50
	1090	8	1700V	150A	2MBI150VH-170-50
	1450	8	1700V	200A	2MBI200VH-170-50
	2180	8	1700V	300A	2MBI300VN-170-50
	2900	8	1700V	400A	2MBI450VN-170-50
	3490	8	1700V	300A x2	2MBI300VN-170-50
10 kV	1200	12	1700V	100A	2MBI100VA-170-50
	1800	12	1700V	150A	2MBI150VH-170-50
	2400	12	1700V	200A	2MBI200VH-170-50
	3600	12	1700V	300A	2MBI300VN-170-50
	4800	12	1700V	400A	2MBI450VN-170-50
	5800	12	1700V	300A x2	2MBI300VN-170-50

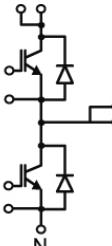
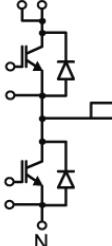
## Feature

- ✓ Low power dissipation with V-silicon chipset
- ✓ Extra thermal design ( $T_{jmax} = 175^{\circ}\text{C}$  repetitive guarantee)
- ✓ Improved thermal cycling capability with new solder
- ✓ Long-term reliability (  $\text{CTI} > 600$ , High  $T_c$  capability)
- ✓ M6 mounting hole for all PKG (except 45mm PKG;M5)

	IGBT P/N	Current	Voltage	Package	Equivalent circuit	Base plate	Isolation
Standard 2in1	2MBI75VA-170-50	75A	1700V	M263:94 x 34 x 30mm 		Copper (Cu)	$\text{Al}_2\text{O}_3$ $V_{iso}=4.0\text{kV}/60\text{s}$
	2MBI100VA-170-50	100A	1700V	M276:108 x 62 x 30.5mm 		Copper (Cu)	$\text{Al}_2\text{O}_3$ $V_{iso}=4.0\text{kV}/60\text{s}$
	2MBI150VH-170-50	150A	1700V			Copper (Cu)	$\text{Al}_2\text{O}_3$ $V_{iso}=4.0\text{kV}/60\text{s}$
	2MBI200VH-170-50	200A	1700V				
	2MBI300VH-170-50	300A	1700V				

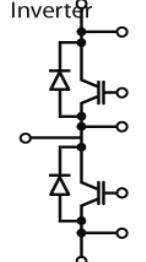
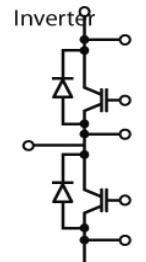
## Feature

- ✓ Low power dissipation with V-silicon chipset
- ✓ Extra thermal design ( $T_{jmax} = 175^\circ\text{C}$  repetitive guarantee)
- ✓ Low inductance and good current balance package
- ✓ Long-term reliability (  $\text{CTI} > 600$ , High  $T_c$  capability)
- ✓ M6 mounting hole for all PKG (except 45mm PKG;M5)

	IGBT P/N	Current	Voltage	Package	Equivalent circuit	Base plate	Isolation
Dual XT	2MBI300VN-170-50	300A	1700V			Copper (Cu)	$\text{Al}_2\text{O}_3$ $\text{Viso}=4.0\text{kV}/60\text{s}$
	2MBI450VN-170-50	450A	1700V				
	2MBI550VN-170-50	550A	1700V				
	2MBI550VJ-170-50	550A	1700V			Copper (Cu)	$\text{Al}_2\text{O}_3$ $\text{Viso}=4.0\text{kV}/60\text{s}$

## Feature

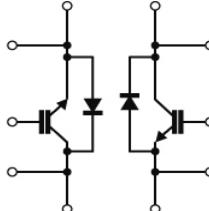
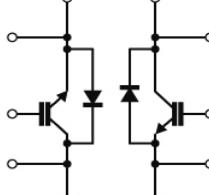
- ✓ Low power dissipation with V-silicon chipset
- ✓ Extra thermal design ( $T_{jmax}=175^{\circ}\text{C}$  repetitive guarantee)
- ✓ Low inductance and good current balance package
- ✓ Long-term reliability (  $\text{CTI} > 600$ , High  $T_c$  capability)

	IGBT part No.	Current	Voltage	Package	Equivalent circuit	Base plate	Isolation
PrimePACK™	2MBI650VXA-170E-50	650A	1700V	M271:172 x 89 x 38mm 		Copper (Cu)	$\text{Al}_2\text{O}_3$ $\text{Viso}=4.0\text{kV}/60\text{s}$
	2MBI1000VXB-170E-50	1000A	1700V	M272:250 x 89 x 38mm 		Copper (Cu)	$\text{Al}_2\text{O}_3$ $\text{Viso}=4.0\text{kV}/60\text{s}$
	2MBI1400VXB-170E-50	1400A	1700V				
	2MBI1400VXB-170P-50	1400A	1700V				

Note: PrimePACK™ are registered trademarks of Infineon Technology AG, Germany.

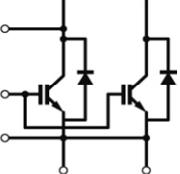
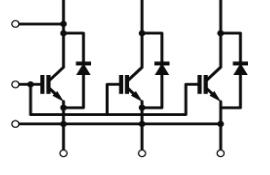
## Feature

- ✓ Low power dissipation with V-silicon chipset
- ✓ Extra thermal design ( $T_{jmax}=175^{\circ}\text{C}$ ), AlSiC base plate
- ✓ Low inductance and good current balance package
- ✓ Long-term reliability (  $\text{CTI} > 600$ , High  $T_c$  capability)

	IGBT part No.	Current	Voltage	Package	Equivalent circuit	Base plate	Isolation
2in1	2MBI600VG-170E	600A	1700V			Copper (Cu)	$\text{Si}_3\text{N}_4$ $V_{iso}=4.0\text{kV}/60\text{s}$
	2MBI800VG-170E	800A	1700V				
	2MBI1200VG-170E	1200A	1700V				
	2MBI600VT-170E	600A	1700V			AlSiC	$\text{AlN}$ $V_{iso}=4.0\text{kV}/60\text{s}$
	2MBI800VT-170E	800A	1700V				
	2MBI1200VT-170E	1200A	1700V				

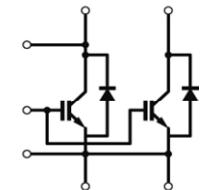
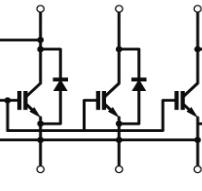
## Feature

- ✓ Low power dissipation with V-silicon chipset
- ✓ Extra thermal design ( $T_{jmax}=175^{\circ}\text{C}$ ), SiN-DCB
- ✓ Low inductance and good current balance package
- ✓ Long-term reliability (  $\text{CTI} > 600$ , High  $T_c$  capability)
- ✓ 1700V-3600A max rating

	IGBT part No.	Current	Voltage	Package	Equivalent circuit	Base plate	Isolation
1in1	1MBI1200VC-170E	1200A	1700V	M151:130 x 140 x 38mm 		Copper (Cu)	$\text{Si}_3\text{N}_4$ $V_{iso}=4.0\text{kV}/60\text{s}$
	1MBI1600VC-170E	1600A	1700V				
	1MBI2400VC-170E	2400A	1700V				
	1MBI2400VD-170E	2400A	1700V	M152:190 x 140 x 38mm 		Copper (Cu)	$\text{Si}_3\text{N}_4$ $V_{iso}=4.0\text{kV}/60\text{s}$
	1MBI3600VD-170E	3600A	1700V				

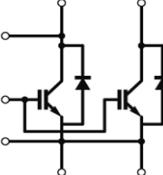
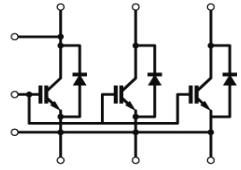
## Feature

- ✓ Low power dissipation with V-silicon chipset
- ✓ Extra thermal design ( $T_{jmax}=175^{\circ}\text{C}$ ), AlSiC base plate
- ✓ Low inductance and good current balance package
- ✓ Long-term reliability (  $\text{CTI} > 600$ , High  $T_c$  capability)
- ✓ 1700V-3600A max rating

	IGBT part No.	Current	Voltage	Package	Equivalent circuit	Base plate	Isolation
1in1	1MBI1200VR-170E	1200A	1700V			AlSiC	AlN $V_{iso}=4.0\text{kV}/60\text{s}$
	1MBI1600VR-170E	1600A	1700V				
	1MBI2400VR-170E	2400A	1700V				
	1MBI2400VS-170E	2400A	1700V			AlSiC	AlN $V_{iso}=4.0\text{kV}/60\text{s}$
	1MBI3600VS-170E	3600A	1700V				

## Feature

- ✓ Trench gate structure for reducing Vce(sat)
- ✓ FS (field-stop) structure for fast switching and low Vce(sat)
- ✓ High ruggedness even at  $T_j = 150^{\circ}\text{C}$  operation
- ✓ High tracking (CTI > 600) special resin for high Viso guarantee
- ✓ High thermal cycling life time with AlSiC base plate

	IGBT part No.	Current	Voltage	Package	Equivalent circuit	Base plate	Isolation
1in1	1MBI800UG-330	800A	3300V	M155:130 x 140 x 38mm 		AlSiC	AlN Viso=6.0kV/60s
	1MBI1000UG-330	1000A	3300V	M156:190 x 140 x 38mm 			
	1MBI1200UE-330	1200A	3300V		AlSiC	AlN Viso=6.0kV/60s	
	1MBI1500UE-330	1500A	3300V				

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<http://igbt-driver.com/>

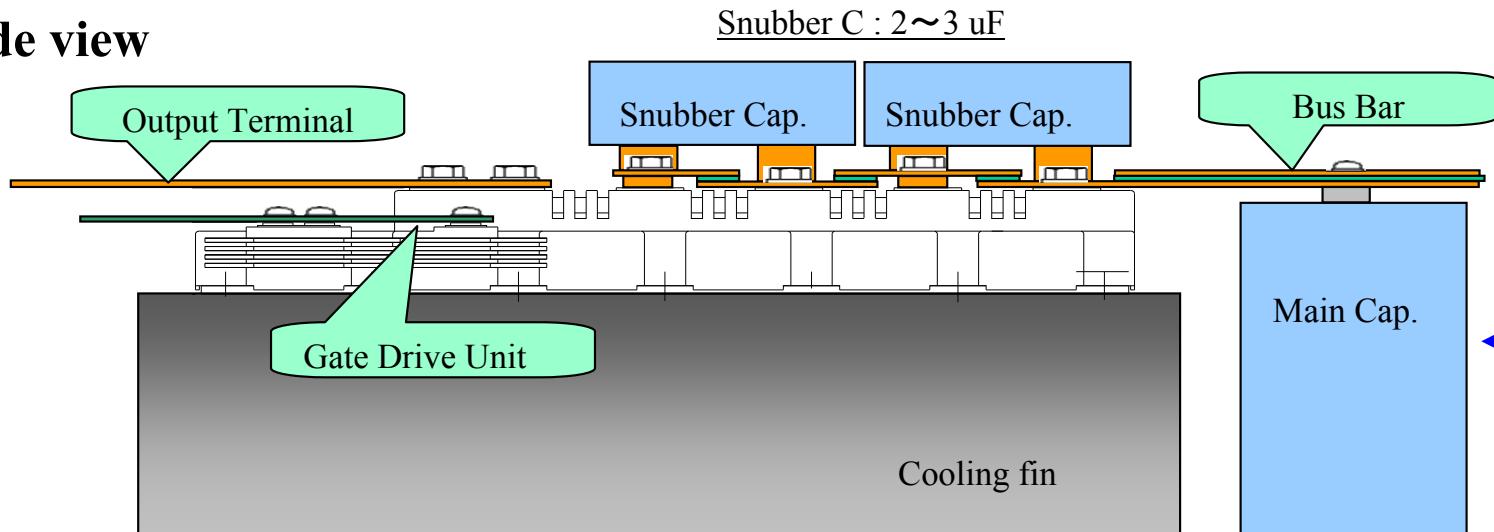
Ic rating	IGBT P/N (example)	Driver type (example)
100A	2MBI100VA-170-50	2SP0115T2Ax
150A	2MBI150VH-170-50	2SP0115T2Ax
200A	2MBI200VH-170-50	2SP0115T2Ax
300A	2MBI300VN-170-50	2SP0115T2Ax
450A	2MBI450VN-170-50	2SP0115T2Ax
550A	2MBI550VN-170-50	2SP0115T2Ax



<http://www.idc-com.co.jp/>

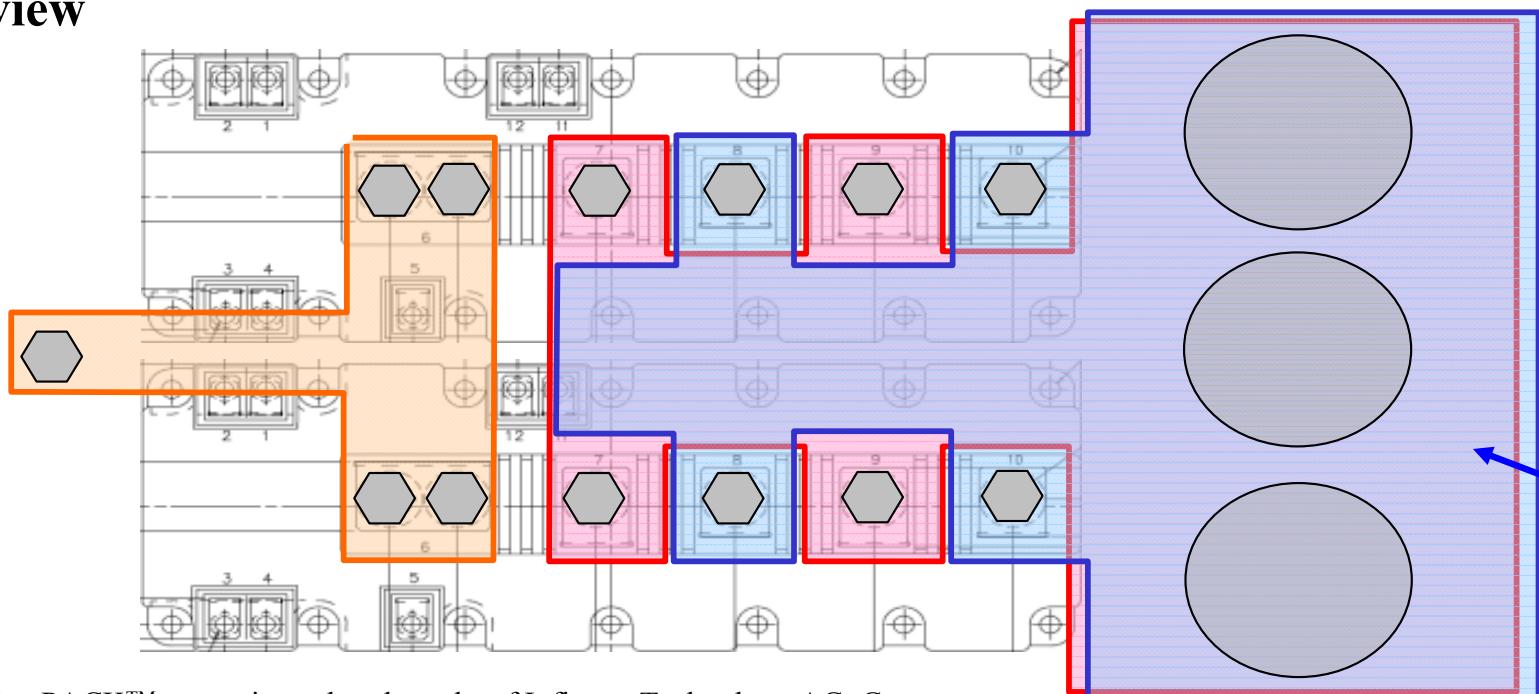
Ic rating	IGBT P/N (example)	Driver type (example)
75A	2MBI75VA-170-50	VLA546**
100A	2MBI100VA-170-50	VLA546**
150A	2MBI150VH-170-50	VLA546**
200A	2MBI200VH-170-50	VLA546**
300A	2MBI300VN-170-50	VLA546**
450A	2MBI450VN-170-50	VLA500K

## Side view



**PrimePACK™ can easily construct inverter circuit . This figure shows the example.**

## Top view



**Laminate bus bar to realize low leakage inductance.**

Note: PrimePACK™ are registered trademarks of Infineon Technology AG, Germany.

# Snubber capacitors

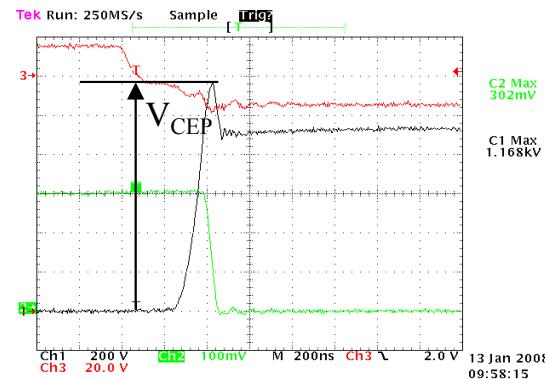
$$C_s = \frac{L * I_o^2}{(V_{CEP} - E_d)^2}$$

L: Main circuit wiring parasitic inductance

I<sub>o</sub>: Collector current at IGBT turn-off

V<sub>CEP</sub>: Snubber capacitor peak voltage

E<sub>d</sub>: DC supply voltage



Module rating		DC line inductance	snubber capacitance
V <sub>ces</sub>	I <sub>c</sub>		
1200V/1700V	100A	0.2 $\mu$ H	0.47 $\mu$ F
	300A	0.1 $\mu$ H	3.3 $\mu$ F
	450A	0.08 $\mu$ H	4.7 $\mu$ F
	1000A	0.07 $\mu$ H	6.8 $\mu$ F
	1400A	0.06 $\mu$ H	12 $\mu$ F